



This certificate is granted and awarded by the authority of the Nadcap Management Council to:

***ADI - Electronics Manufacturing Technologies Pvt Ltd -
CCA***

*Sy No 10/1A Whitefield Road, Hoody K.R. Puram Hobli
Bangalore, KA 560048
India*

This certificate demonstrates conformance and recognition of accreditation for specific services, as listed in www.eAuditNet.com on the Qualified Manufacturers List (QML), to the revision in effect at the time of the audit for:

Electronics

Certificate Number: 11807186454
Expiration Date: 31 January 2020

Joseph G. Pinto
Executive Vice President and Chief Operating Officer



SCOPE OF ACCREDITATION

Electronics

ADI - Electronics Manufacturing Technologies Pvt Ltd - CCA
Sy No 10/1A Whitefield Road, Hoody K.R. Puram Hobli
Bangalore, KA 560048
India

This certificate expiration is updated based on periodic audits. The current expiration date and scope of accreditation are listed at: www.eAuditNet.com - Online QML (Qualified Manufacturer Listing).

In recognition of the successful completion of the PRI evaluation process, accreditation is granted to this facility to perform the following:

AC7120 Rev E - Nadcap Audit Criteria for Circuit Card Assemblies (to be used on audits on/after 9 April 2017)

- 04– General
- 06– Process Control
- 07– Visual Acuity
- 08– Customer Data
- 09– Electrostatic Discharge (ESD)
- 10– Material Management
- 11– Moisture Sensitive Components and Materials
- 12– Kitting
- 13.1– In–Process Verification / Inspection: General
- 13.2– In–Process Verification / Inspection: Visual
- 13.3– In–Process Verification / Inspection: AOI
- 13.4– In–Process Verification / Inspection: X–Ray
- 14.1– Secondary Assembly: Mechanical Part Installation
- 14.2– Secondary Assembly: Wire Cutting & Stripping
- 14.3– Secondary Assembly: Jumper Wire Installation
- 14.4– Secondary Assembly: Stranded Wire Tinning
- 14.6– Secondary Assembly: Bonding
- 15– Cleanliness
- 16– Final Inspection
- 17– Rework

AC7120/2 - General Soldering of Printed Board Assemblies (to be used on audits on/after 9

April 2017)

- 03– General
- 04– Electronic Component Preparation for Preassembly Process
- 05.1– Part Placement: General
- 05.2– Part Placement: Manual
- 05.3– Part Placement: Clinched Component Leads
- 07– Build Through / Build Short
- 08– Hand Soldering

AC7120/3 - Plated Through Hole Technology (to be used on audits on/after 9 April 2017)

- 03.1– Part Placement: Operator–Assisted (Semi–Automated)
- 04– Wave Soldering

AC7120/4 - Surface Mount Technology (to be used on audits on/after 9 April 2017)

- 03– Preparation
- 04– Stencil Printing
- 05– Automated Part Placement
- 06– Reflow Soldering

AC7120/7 - Conformal Coating of Printed Board Assemblies (to be used on audits on/after 9 April 2017)

- 04– Material
- 05– Material and Equipment Compatibility
- 06– Preparation / Cleaning
- 07– Application / Drying / Curing
- 08– Thickness
- 09– Inspection
- 10– Rework
- 11– Training

AC7120/8 - Encapsulation (to be used on audits on/after 9 April 2017)

AC7120/9 - Programming (to be used on audits on/after 9 April 2017)

- 04– General
- 05– Component Programming (Prior to Assembly)
- 06– Circuit Card Assembly Programming

AC7120/10 - Final Testing (to be used on audits on/after 9 April 2017)

- 04– General